

Electronic Patent Application Fee Transmittal

Application Number:	10500494			
Filing Date:	27-Dec-2004			
Title of Invention:	Method of forming copper interconnections for semiconductor integrated circuits on a substrate			
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Filer:	Adeel S. Akhtar/Debbie Fonseca			
Attorney Docket Number:	ASMGEN.003APC			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810